

ENGINEERING DEPT.	PRODUCT SPECIFICATION For CJCL Series Board Mound Telephone Jack	SPEC.NO.: SPCJ066A
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1. SCOPE:

This specification contains the test requirement of subject connectors when tested under the condition and below standards base on CviLux test procedure

2. APPLICABLE STANDARDS:

MIL - STD - 202 Methods for test of connectors for electronic equipment
MIL - STD - 1344 Test methods for electrical connectors

3. APPLICABLE SERIES NO.: CJCL88AB1D2

4. SHAPE, CONSTRUCTION AND DIMENSIONS

See attached drawings

5. MATERIALS

See attached drawings

6. ACCOMMODATED P.C.BOARD

6.1 Thickness: 1.6 mm (.063")

6.2 P.C. Board Layout: See attached drawings



REVIEWED : Eisley APPROVED : Eisley VERIFIED : Sandy .



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7. ELECTRICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
7.1	Rated current and voltage		1.5 A Max 150 V AC (r.m.s.)
7.2	Contact resistance	Open circuit of DC 20 mV max. 100 mA Max. EIA-364-23B	Less than 20 mΩ (Initial) Less than 30 mΩ (Final)
7.3	Dielectric strength	Input to Output 1000V AC / 60 sec Current leakage: 1 mA max. EIA-364-20B	No change
7.4	Insulation resistance	When applied DC 500 V between adjacent terminal or ground EIA-364-21C	More than 1000 MΩ

8. MECHANICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
8.1	Durability	Mate and unmated for 750 cycles Operation Speed : 25mm / min EIA-364-09C	Appearance: No damage
8.2	Mating force	Measure force to mate samples at speed 25±3mm per minute with plug latch depressed EIA-364-13B	8 contacts: 2.24 Kgf (22 N) Max.

9. ENVIRONMENTAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
9.1	Humidity test	At a temperature of 40±2°C and relative humidity of 90-95% for 8 hours EIA-364-31B	Appearance: No damage
9.2	Temperature Life	Exposing in a heat chamber at a temperature of 105±5°C for 8 hours EIA-364-17B	Appearance: No damage Dielectric strength: To pass para 7-3 Insulation resistance: To pass para 7-4

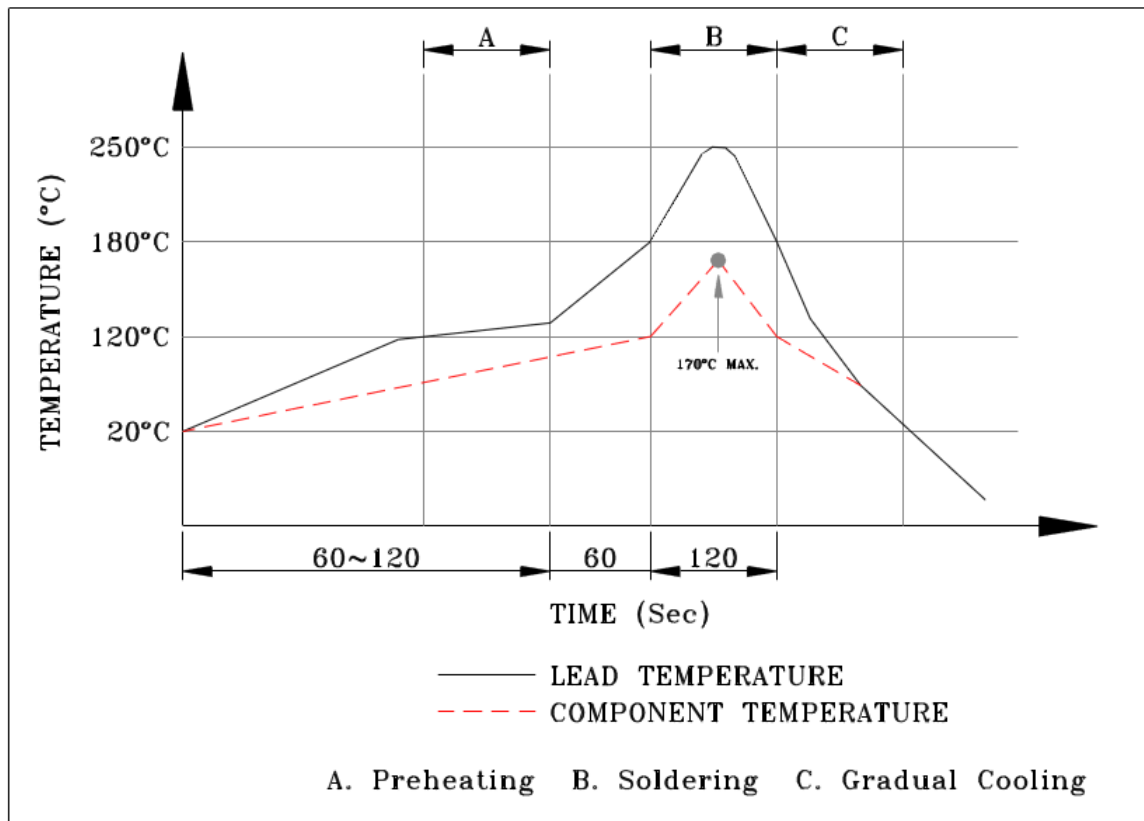


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	ITEM	TEST CONDITION	REQUIREMENT
9.3	Salt spray	Temperature: $35 \pm 2^{\circ}\text{C}$ Solution: $5 \pm 1\%$ Spray time: 8 hours After test, rinse the sample with water and recondition the room temperature for 1 hour. EIA-364-26B	Appearance: No damage
9.4	Solder ability	Soldering time: 5 ± 0.5 second Soldering pot: $245 \pm 5^{\circ}\text{C}$	Minimum: 95% of immersed area
9.5	Resistance to soldering heat	Recommend Wave Soldering Profile (11.)	No damage

10. OPERATING TEMPERATURE RANGE: -40 to $+85^{\circ}\text{C}$

11. Recommend Wave Solder Profile



SUGGESTED WAVE SOLDER CURVE

- (1) Tip temperature : $250 \pm 10^{\circ}\text{C}$
 - (2) Tip temperature time : 5sec max
- * The melting point of Tin: 183°C